

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add vendor CAGE 48726 to the 02XX device. Make corrections to tables I and II. Change name and address for CAGE U4637. Inactivate 01 device for new design. Make changes to 6.4.	88-12-02	M. A. FRYE
B	Add vendors CAGE 69210 and 27014. Add case outlines T and U. Editorial changes throughout.	91-11-04	M. A. FRYE
C	Changes in accordance with NOR 5962-R231-96.	96-09-30	R. MONNIN
D	Add radiation hardness requirements. Redrawn. -rrp	00-03-28	R. MONNIN
E	Add case outlines Y and Z. Make change to load regulation test for case outline T as specified in table I - ro	02-05-14	R. MONNIN

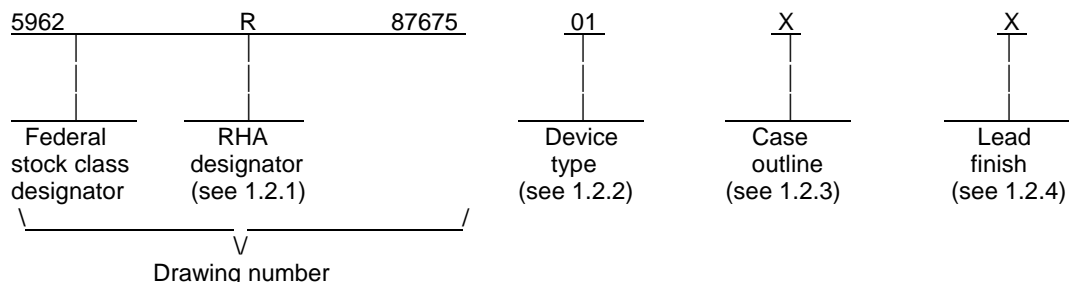
THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

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REV STATUS				REV		E	E	E	E	E	E	E	E	E	E	E	E	E	E													
OF SHEETS				SHEET		1	2	3	4	5	6	7	8	9	10	11	12	13														
PMIC N/A				PREPARED BY JOSEPH A. KERBY					DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216 http://www.dscc.dla.mil																							
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A				CHECKED BY CHARLES E. BESORE																												
				APPROVED BY MICHAEL A. FRYE																												
				DRAWING APPROVAL DATE 87-11-18																												
				REVISION LEVEL E					SIZE A	CAGE CODE 67268		5962-87675																				
										SHEET 1 OF 13																						

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 RHA designator. RHA marked devices shall meet the MIL-PRF-38535 or MIL-PRF-38535, Appendix A specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	150	3.0 A positive regulator, adjustable
02	150A	3.0 A positive regulator, adjustable

1.2.3 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
T	See figure 1	3	TO-257 Single row flange mount with non-isolated tab and glass sealed
U	See figure 1	3	TO-257 Single row flange mount with isolated tab and glass sealed
X	MBFM1-P2	2	TO-3 Flange mount
Y	See figure 1	3	Flange mount, glass sealed with gull wing leads
Z	CBCC1-N3	3	Bottom terminal chip carrier

1.2.4 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Input to output voltage differential	35 V
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Power dissipation (P _D)	Internally limited 1/

1/ Power dissipation is guaranteed at 30 W up to 15 V input-output differential. Above 15 V, input-output differential power dissipation is limited by device internal protection circuitry.

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1.3 Absolute maximum ratings – Continued.

Thermal resistance, junction-to-case (θ_{JC}):

Case T	3.5°C/W
Case U	4.2°C/W
Case X	1.5°C/W
Case Y	6.4°C/W
Case Z	3.7°C/W
Junction temperature (T_J)	+150°C

1.4 Recommended operating conditions.

Ambient operating temperature range (T_A) -55°C to +125°C

1.5 Radiation features:

Maximum total dose available (dose rate = 50 – 300 rads(Si) / s) 100 Krad 2/

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

2/ These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.

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3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.3 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be as specified on figure 3.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/ 2/ 3/</u> -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit		
					Min	Max			
Reference voltage	V _{REF}	I _{OUT} = 10 mA, T _A = +25°C	1	01	1.20	1.30	V		
		I _{OUT} = 10 mA, T _A = +25°C	1	02	1.238	1.262			
		M,D,P,L,R	1		1.238	1.262			
		3.0 V ≤ (V _{IN} – V _{OUT}) ≤ 35 V 10 mA ≤ I _{OUT} ≤ 3.0 A, P ≤ 30 W <u>4/</u>	1,2,3	01	1.20	1.30			
		3.0 V ≤ (V _{IN} – V _{OUT}) ≤ 35 V 10 mA ≤ I _{OUT} ≤ 3.0 A, P ≤ 30 W <u>4/</u>	1,2,3	02	1.225	1.270			
		M,D,P,L,R	1		1.225	1.270			
Line regulation <u>5/</u>	ΔV _{OUT} / ΔV _{IN}	3.0 V ≤ (V _{IN} – V _{OUT}) ≤ 35 V I _{OUT} = 10 mA, T _J = +25°C	1	01,02		0.01	%V		
		M,D,P,L,R	1	02		0.01			
		3.0 V ≤ (V _{IN} – V _{OUT}) ≤ 35 V I _{OUT} = 10 mA	2,3	01,02		0.05			
Load regulation <u>5/ 6/</u>	ΔV _{OUT} / ΔI _{OUT}	10 mA ≤ I _{OUT} ≤ 3.0 A V _{OUT} ≤ 5.0 V, T _J = +25°C	Cases X and Z	1	01,02		15	mV	
		Cases T, U, and Y				17.5			
		M,D,P,L,R	Case U	1	02		17.5		
		10 mA ≤ I _{OUT} ≤ 3.0 A, V _{OUT} ≤ 5.0 V		2,3	01,02		50		
		10 mA ≤ I _{OUT} ≤ 3.0 A V _{OUT} ≥ 5.0 V, T _J = +25°C	Cases X and Z	1			0.3		%
		Cases T, U, and Y				0.35			
		M,D,P,L,R	Case U	1		02			0.35
		10 mA ≤ I _{OUT} ≤ 3.0 A, V _{OUT} ≥ 5.0 V		2,3	01,02		1.0		

See footnotes at end of table.

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COLUMBUS, OHIO 43216-5000

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions <u>1/ 2/ 3/</u> -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Thermal regulation	----	20 ms pulse, T _A = +25°C	1	01,02		0.01	%W
		M,D,P,L,R	1	02		0.01	
Ripple rejection <u>7/</u>	$\Delta V_{IN}/$ ΔV_{REF}	V _{OUT} = 10 V, f = 120 Hz, C _{ADJ} = 10 μF	4,5,6	01,02	66		dB
		M,D,P,L,R	4	02	66		
Adjust pin current	I _{ADJ}		1,2,3	01,02		100	μA
		M,D,P,L,R	1	02		100	
Adjust pin current change	ΔI_{ADJ}	10 mA ≤ I _{OUT} ≤ 3.0 A, I _{OUT} = 10 mA, 3.0 V ≤ (V _{IN} - V _{OUT}) ≤ 35 V	1,2,3	01,02		5.0	μA
		M,D,P,L,R	1	02		5.0	
Minimum load current	I _{MIN}	(V _{IN} - V _{OUT}) = 35 V	1,2,3	01,02		5.0	mA
		M,D,P,L,R	1	02		5.0	
Current limit	I _{CL} or	(V _{IN} - V _{OUT}) ≤ 10 V	1,2,3	01,02	3.0		A
		M,D,P,L,R	1	02	3.0		
	I _{SC}	(V _{IN} - V _{OUT}) = 30 V	1,2,3	01,02	0.3		
		M,D,P,L,R	1	02	0.3		
Temperature <u>7/</u> stability	$\Delta V_{OUT}/$ ΔT	-55°C ≤ T _J ≤ +125°C	1,2,3	02		2.0	%
		M,D,P,L,R	1			2.0	
Long term stability <u>7/</u>	$\Delta V_{OUT}/$ ΔT	T _A = +125°C, t = 1000 hours	2	01,02		1.0	%

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

- 1/ Devices supplied to this drawing will meet all levels M, D, P, L, R of irradiation. However, this device is only tested at the 'R' level. Pre and Post irradiation values are identical unless otherwise specified in table I. When performing post irradiation electrical measurements for any RHA level, $T_A = +25^{\circ}\text{C}$.
- 2/ These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.
- 3/ Unless otherwise specified, these specifications apply for $(V_{IN} - V_{OUT}) = 5.0\text{ V}$ and $I_{OUT} = 1.5\text{ A}$. Although power dissipation is internally limited, these characteristics are applicable for power dissipation up to 30 W.
- 4/ Cases T, U, Y, and Z: For output voltage readings not taken at the case, decrease minimum limits by I_{OUT} (10 mΩ) per inch of case to measurement-point lead length, e.g., 15 mV per inch at 1.5 A and 30 mV per inch at 3.0 A.
- 5/ Regulation is measured at a constant junction temperature using a pulse technique. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.
- 6/ Cases T, U, Y, and Z: For load regulation readings not taken at the case, increase maximum limits by I_{OUT} (10 mΩ) per inch of case to measurement-point lead length, e.g., 30 mV per inch at 3.0 A.
- 7/ Guaranteed, if not tested, to the limits specified.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

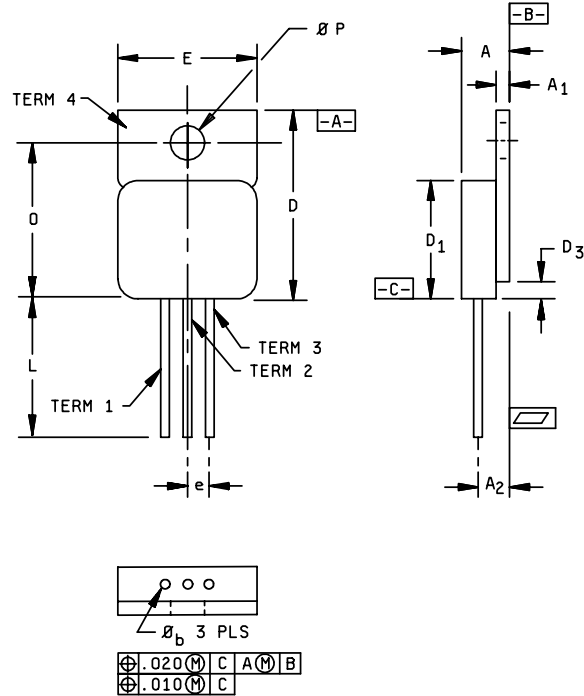
4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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Case outlines T and U



Letter	Inches		Millimeters	
	Min	Max	Min	Max
A	.190	.200	4.83	5.08
A1	.035	.045	0.89	1.14
A2	.120 BSC		3.05 BSC	
ϕb	.025	.035	0.64	0.89
D	.645	.665	16.38	16.89
D1	.410	.430	10.41	10.92
D3	.000	.065	0.00	1.65
e	.100 BSC		2.54 BSC	
E	.410	.422	10.41	10.71
L	.500	.750	12.70	19.05
O	.527	.537	13.39	16.64
ϕP	.140	.150	3.56	3.81

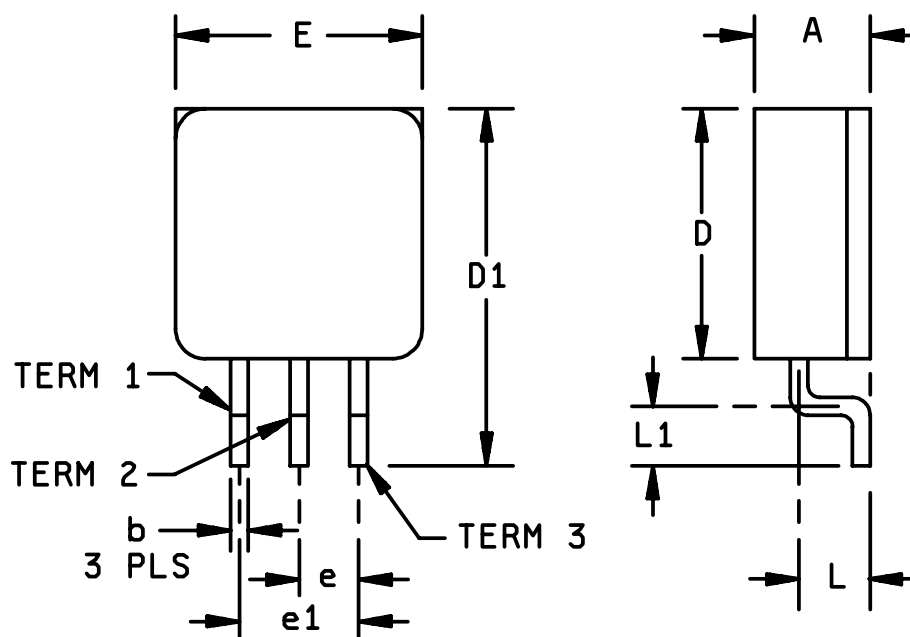
NOTE:

The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

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Case outline Y



Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A	.190	.210	4.83	5.33
b	---	.030	---	0.76
D	.410	.430	10.41	10.92
D1	.580	.610	14.73	15.49
e	---	.100	---	2.54
e1	---	.200	---	5.08
E	.410	.420	10.41	10.67
L1	.090	.110	2.29	2.79
L	.115	.125	2.92	3.18
N	3		3	

NOTE:

The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline – Continued.

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Device types	01 and 02			01	01
Case outlines	T	U	X	Y	Z
Terminal number	Terminal symbol				
1	ADJUST	ADJUST	ADJUST	ADJUST	INPUT
2	OUTPUT	OUTPUT	INPUT	OUTPUT	ADJUST
3	INPUT	INPUT	OUTPUT (CASE)	INPUT	OUTPUT
4	OUTPUT	NC	---	---	---

NC = No connection

FIGURE 2. Terminal connections.

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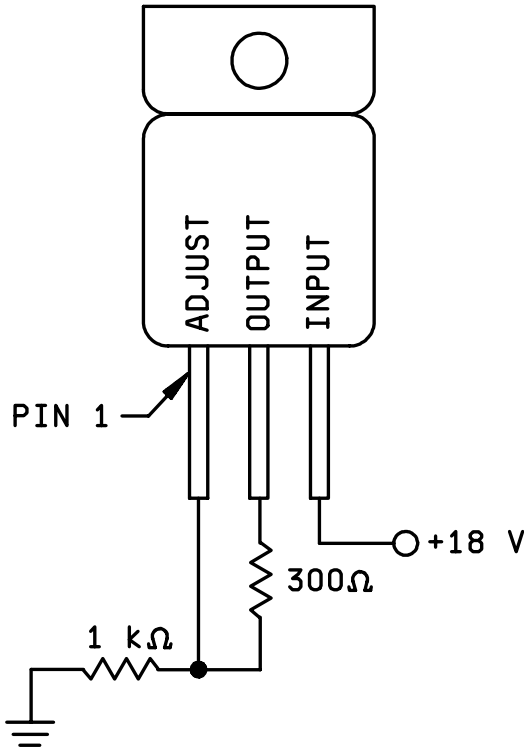


FIGURE 3. Radiation exposure circuit.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3
Group A test requirements (method 5005)	1, 2, 3, 4**, 5**, 6**
Groups C and D end-point electrical parameters (method 5005)	1
Group E end-point electrical parameters (method 5005)	1, 4

* PDA applies to subgroup 1.

** Subgroups 4, 5, and 6, if not tested, shall be guaranteed to the limits specified in table I.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.3 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be as specified in MIL-PRF-38535 or MIL-PRF-38535, Appendix A. End-point parameters shall be as specified in table II herein.

4.3.3.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A and as specified herein.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

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6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 02-05-14

Approved sources of supply for SMD 5962-87675 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /	Reference military specification PIN
5962-8767501TA	69210	OM3910NT/883B	---
	U3158	IP150G/883B	---
	<u>3</u> /	UC150G/883B	---
5962-8767501UA	69210	OM3910ST/883B	---
	U3158	IP150IG/883B	---
	<u>3</u> /	UC150IG/883B	---
5962-8767501XA	27014	LM150K/883	M38510/11705BYA
	U3158	IP150K/883B	---
	<u>3</u> /	LM150K/883B	---
	<u>3</u> /	SG150K/883B	---
	<u>3</u> /	UC150K/883B	---
5962-8767501YA	69210	OM3910SRM/883B	---
5962-8767501ZA	69210	OM3910N5M/883B	---
5962-8767502TA	69210	OM3911NT/883B	---
	U3158	IP150AG/883B	---
	<u>3</u> /	UC150AG/883B	---

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>	Reference military specification PIN
5962-8767502UA	69210	OM3911ST/883B	---
	U3158	IP150AIG/883B	---
	<u>3/</u>	UC150AIG/883B	---
	<u>3/</u>	OM7604STM	---
5962-8767502XA	U3158	IP150AK/883B	----
	<u>3/</u>	LM150AK/883B	----
	<u>3/</u>	SG150AK/883B	----
	<u>3/</u>	UC150AK/883B	----
5962R8767502UA	69210	OMR3911STM/883B	----

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE
number

27014

69210

Vendor name
and address

National Semiconductor
2900 Semiconductor Drive
P.O. Box 58090
Santa Clara, CA 95052-8090

Omnirel Corporation
205 Crawford Street
Leominster, MA 01453-2353

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

Vendor CAGE
number

Vendor name
and address

U3158

SEMELAB PLC
Coventry Road, Lutterworth,
Leicestershire LE174JB
United Kingdom
Point of contact: Martinez & Associates
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